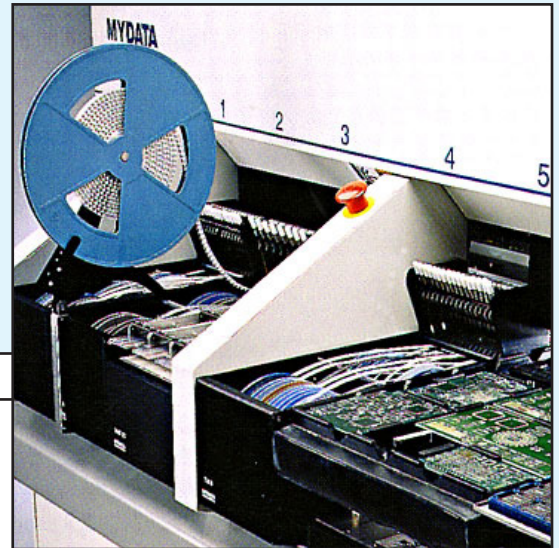


## SMD component placement

PCB cleaning before placing the components, automatic screen printing of the solder paste or using manual dispenser (for samples only), one-side or two-sides component placement on automatic or semi-automatic pick and place machines, infrared reflow ovens with conventional support, cleaning of PCBs after soldering in cleaning machine with ultrasound device, 100% optical check of every PCB, electrical test possible.

Visual system for repairs for components with pitch up to 0.3 mm.



### Automatic pick-and-place

max. PCB dimension:	300 x 200 mm
component dimensions:	0402 to QFP, BGA with pitch 0.3 mm
capacity:	60 000 components./day
possible electronic check of R,C,D,T components	
required production data:	films for tin mask or screen or stencil (frame specified by us) placement data in CAD (Protel 3.6) placement drawing, BOM technological holes on PCBs for placing in the machine (ø 3) reference points for automatic placement

### Semi-automatic pick-and-place

max. PCB design:	300 x 200mm
component dimensions:	0603 do PLCC84.
capacity:	4 000 components./day
required production data:	for serial production: films for tin mask or screen or stencil (frame specified by us), for samples production: solder paste dispensation on manual dispenser placement data in CAD (Protel 3.6) placement drawing, BOM technological holes on PCBs for placing in the machine (ø 3)

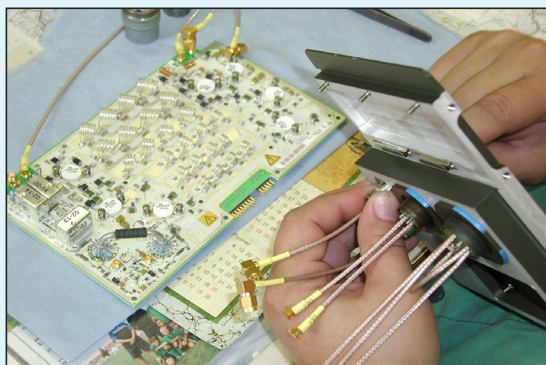
### Standard delivery terms

serial production:	2 weeks
samples and prototypes:	up to 3 days

Dodavatel vojenské techniky podle  
**AQAP 110**  
Quality Assurance Requirements for Design



## Through-hole components placement



### Technological process:

PCB cleaning before placing the components, manual placement of through-hole components, solder-wave or manual soldering, cleaning of PCBs after soldering in cleaning machine with ultrasound device, 100% optical check of every PCB, electrical test possible.

max. PCB dimensions:	300 x 200 mm
max. PCB dimensions:	100 pcs of PCBs (4 000 components)
required production data:	placement drawing, BOM, technological holes on PCBs for placing in the machine (ø 3)

## Electronic devices assembly

SMT and mixed technology component placement single- or double-sides, debugging, production of cables, assembly of electronic sub-assemblies including final measurement, burn-in (temperature range from -60 °C to +85 °C), output quality check.

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